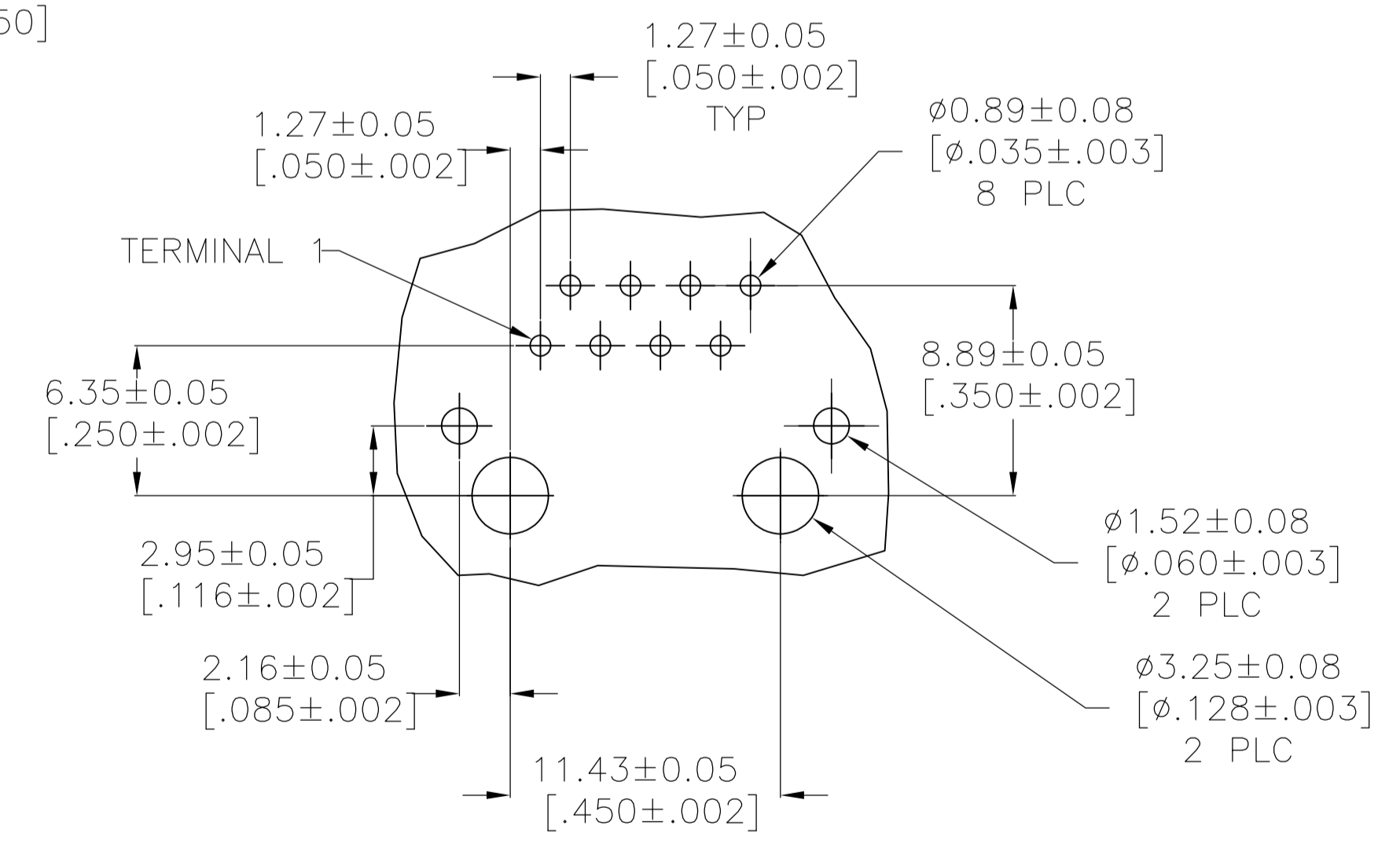
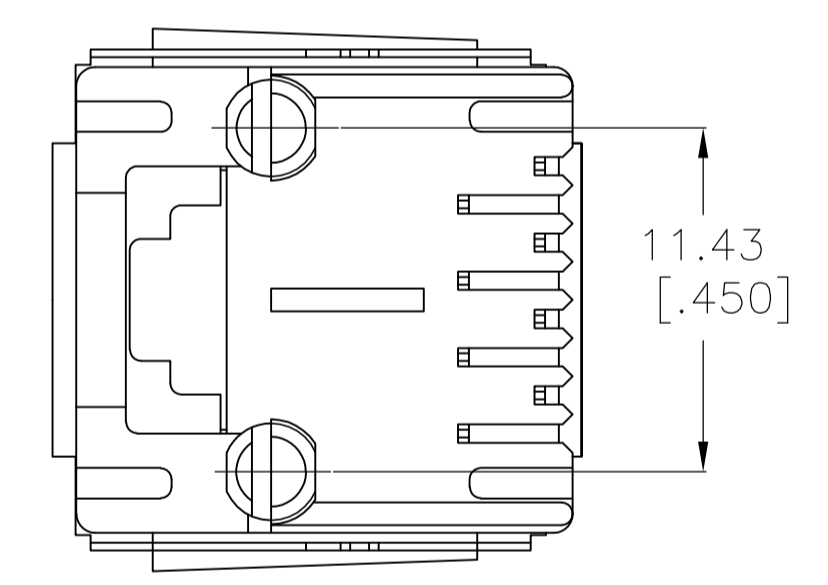
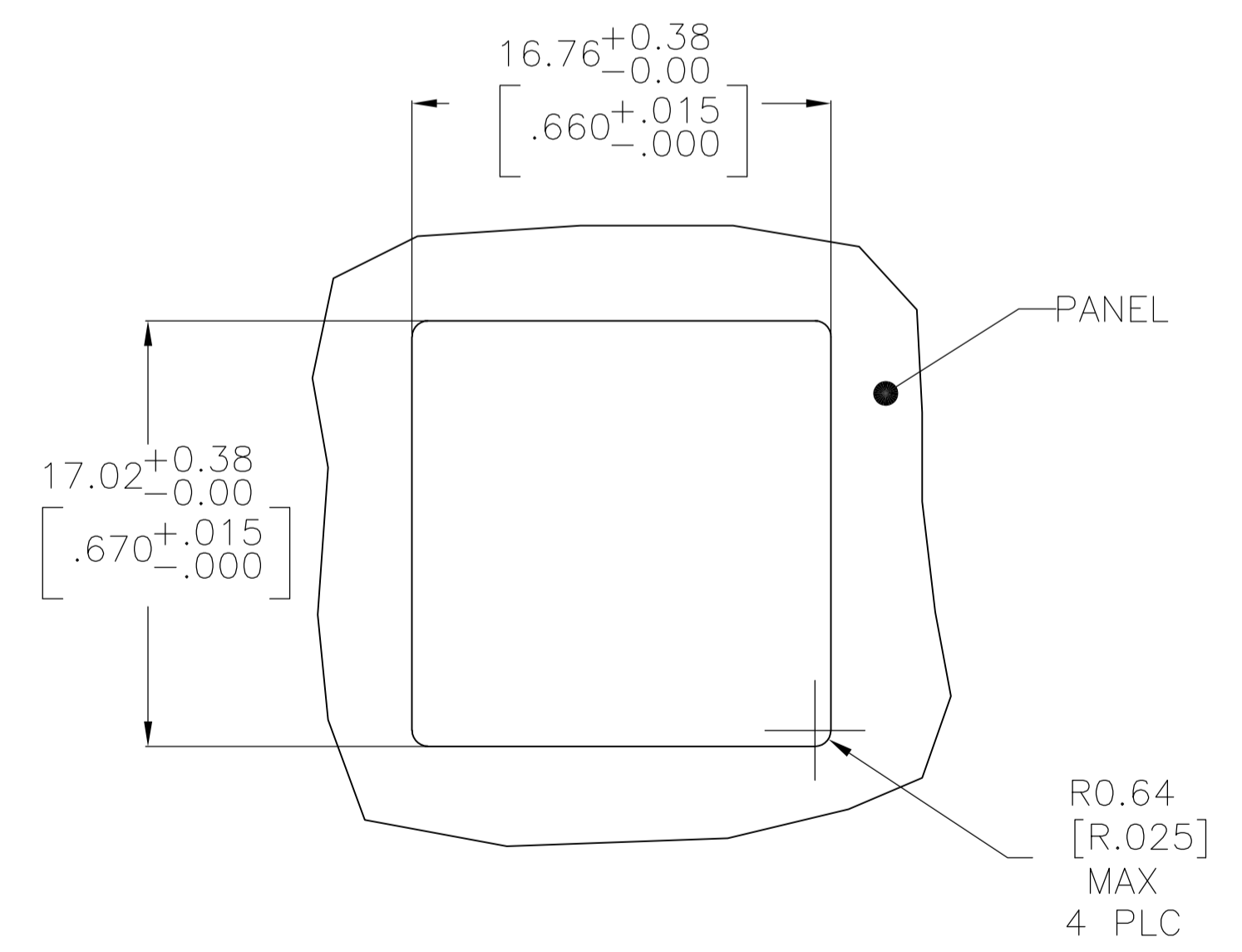


1. MATERIAL:  
 HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK  
 TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81μm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MIN THICK NICKEL UNDERPLATE  
 SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0μm [.000120] MIN THICK REFLOWED TIN.

2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN



RECOMMENDED PANEL CUTOUT

5557730-1  
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN	D. STRAUSSER	22APR2005	Tyco Electronics Corporation Harrisburg, PA 17105-3608
DIMENSIONS: mm [INCHES]		CHK	J. WESTMAN	22APR2005	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD	S. FLICKINGER	22APR2005	NAME: MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, KEYED WITH PANEL STOPS, PANEL AND PCB GROUNDS
0 PLC ± -		PRODUCT SPEC	108-1163		
1 PLC ± -		APPLICATION SPEC	114-2048		
2 PLC ± -		SIZE	A1	00779	SCALE 4:1
3 PLC ± 0.13(.005)		WEIGHT	5557730		SHEET 1 OF 1
4 PLC ± -		CUSTOMER DRAWING	SCALE 4:1		REV C
ANGLES ± -					